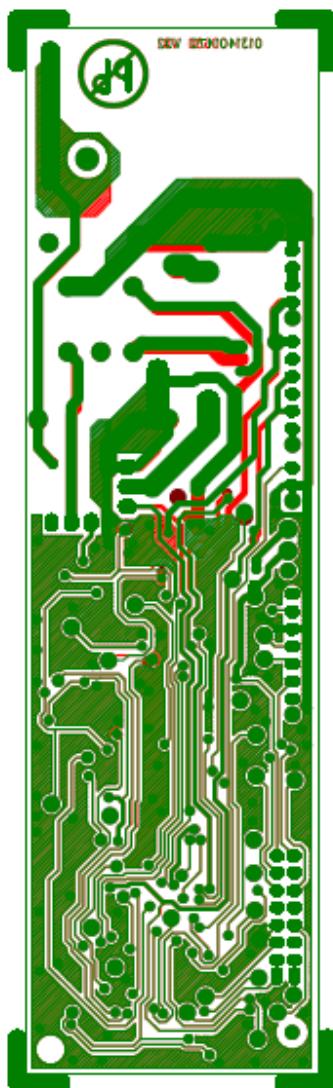


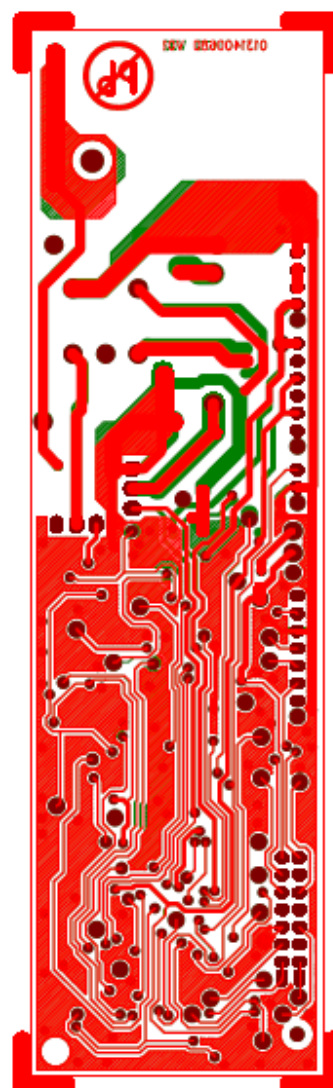
Description of the changes regarding the GX 3 - electronics

Jan. 08, 2016

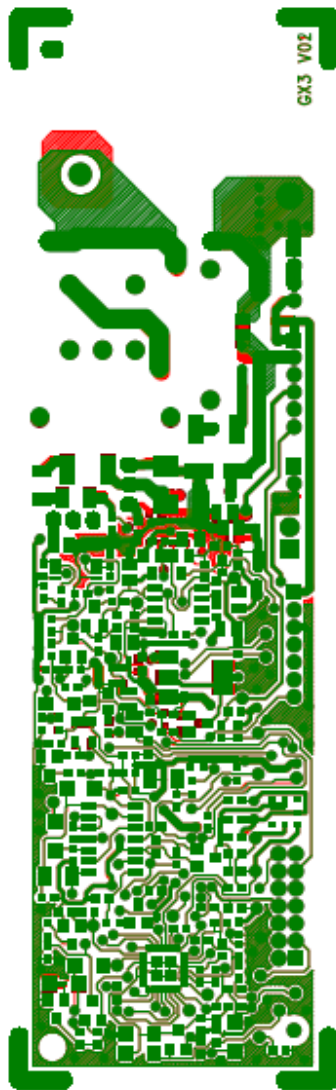
Main unit – difference of the printed circuit board (V01-layout in green, V02-layout in red)



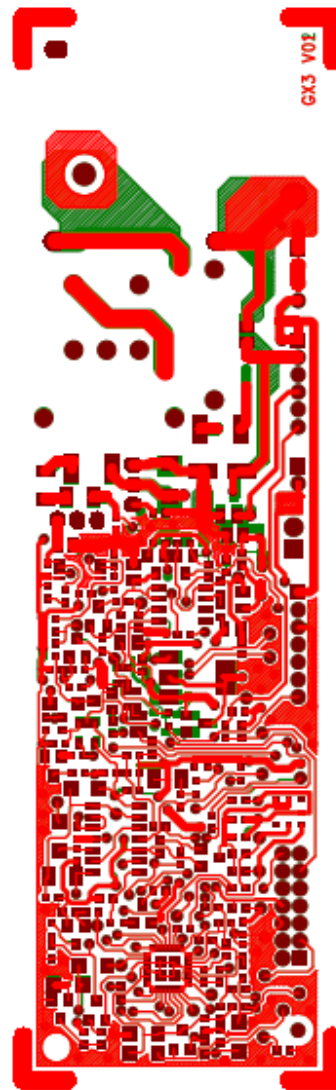
Bottom view
V01-layout red below, V02-layout green above



Bottom view
V01-layout red above, V02-layout green below

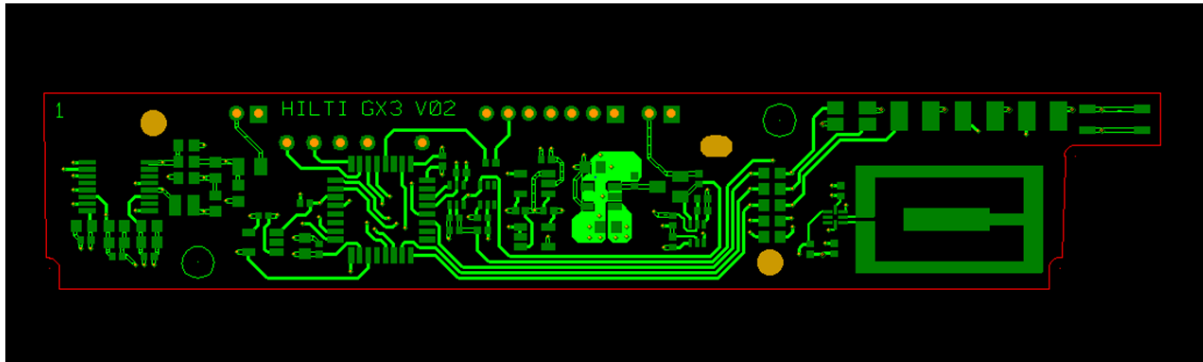


Top view
V01-layout red below, V02-layout green above

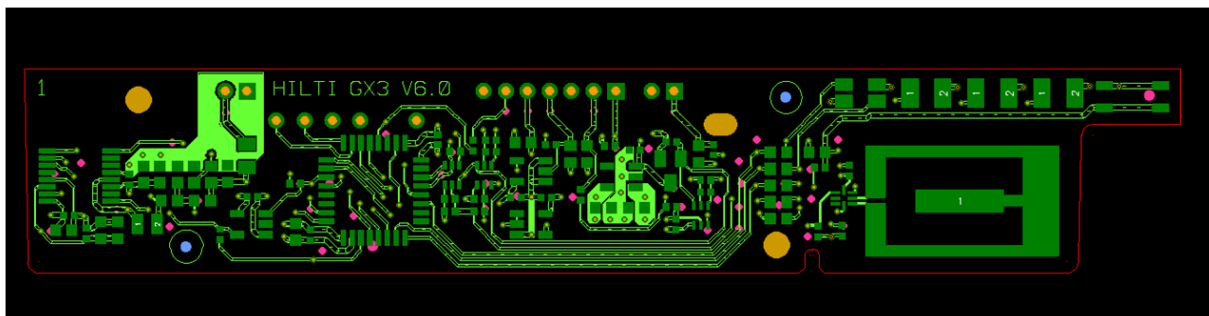


Top view
V01-layout red above, V02-layout green below

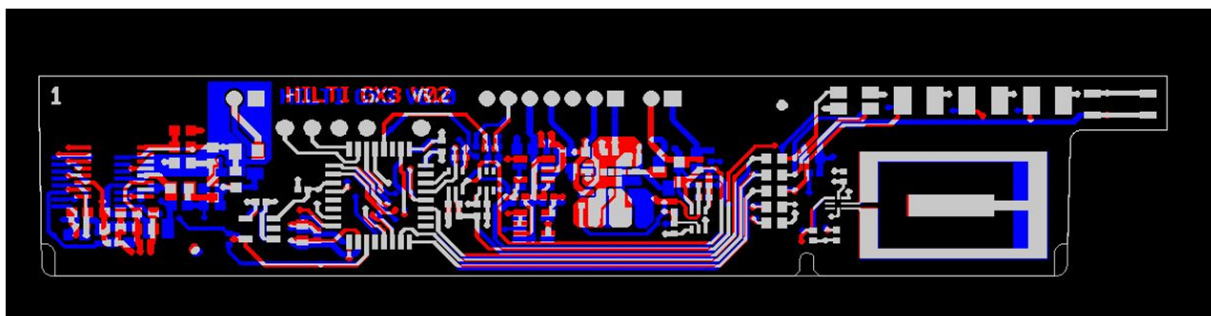
Reader unit – difference of the printed circuit board (V02 versus V06)



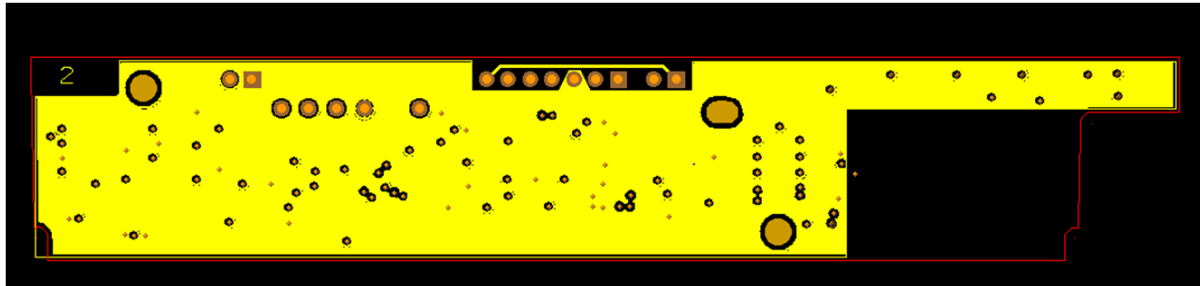
Top-view V02-layout



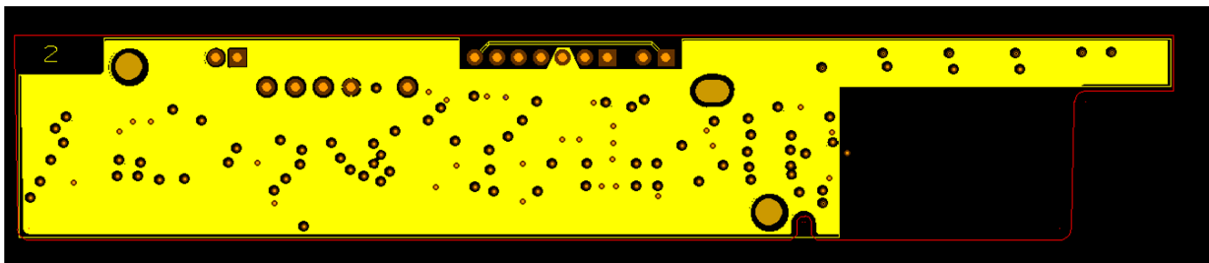
Top-view V06-layout



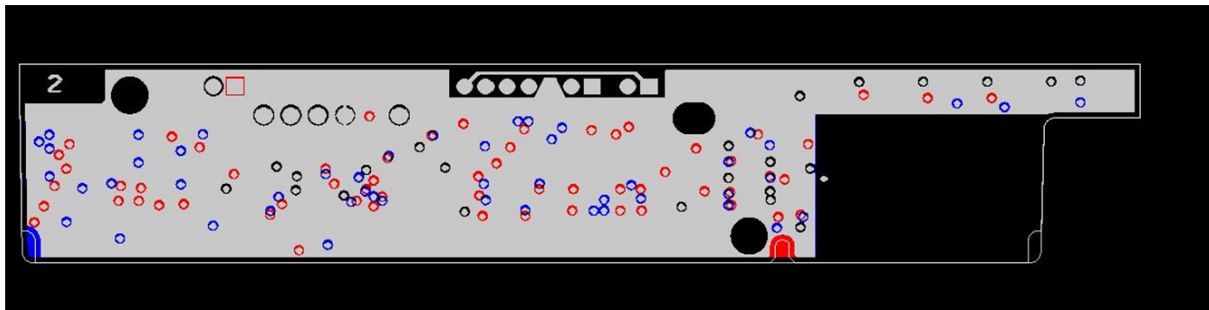
Top view - V02-layout red, V06-layout blue



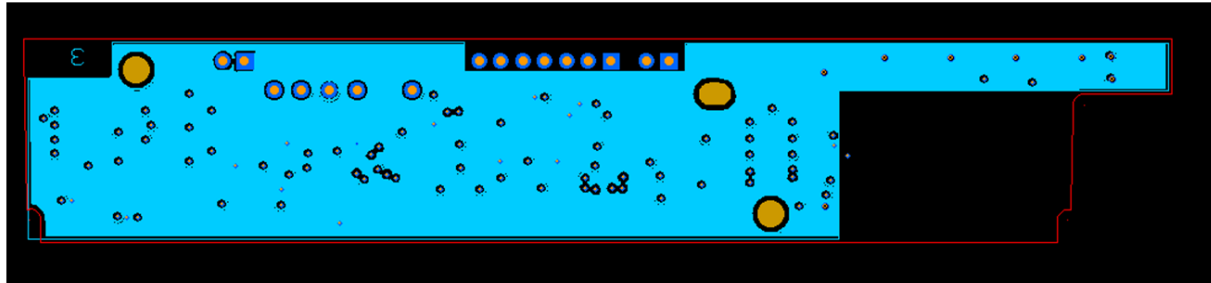
Multilayer 1 - V02-layout



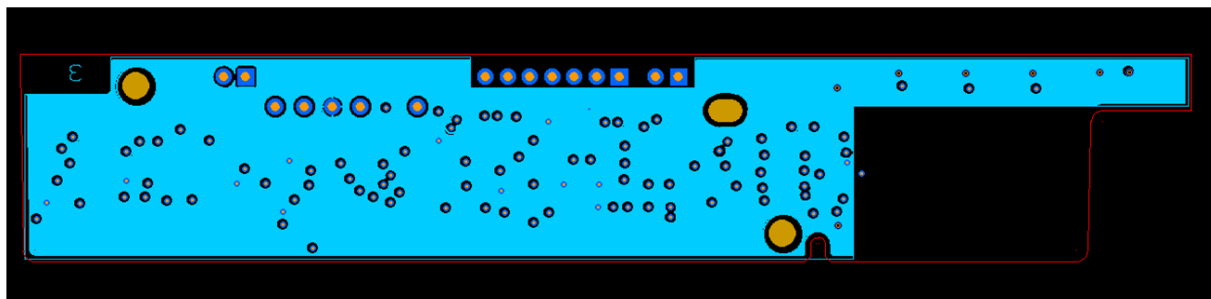
Multilayer 1 - V06-layout



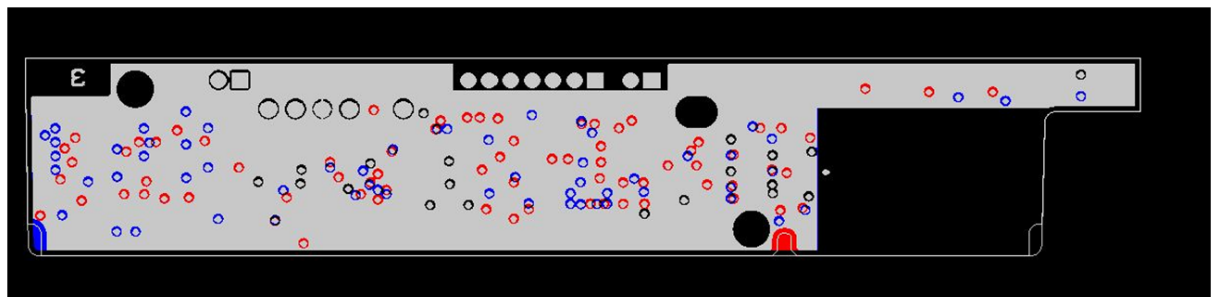
Multilayer 1 V02-layout, black and blue representing holes in the layer,
V06-layout, black and red representing holes in the layer



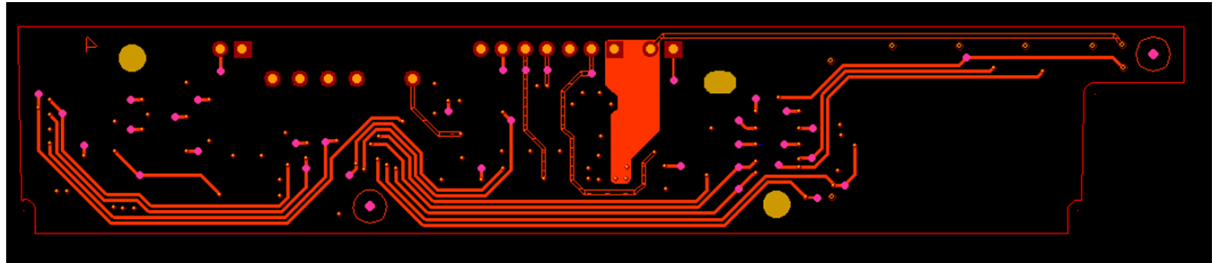
Multilayer 2 - V02-layout



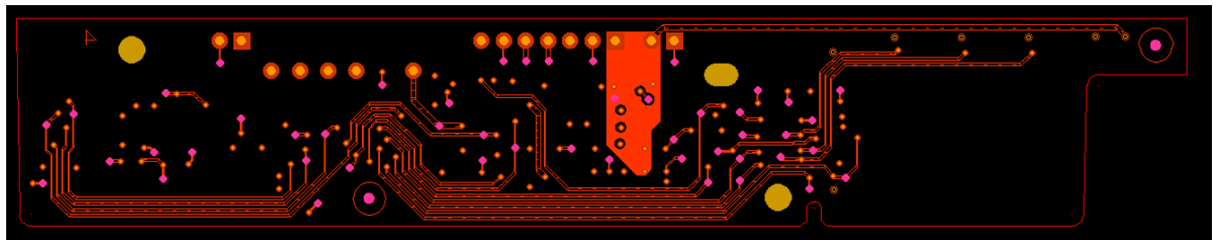
Multilayer 2 - V06-layout



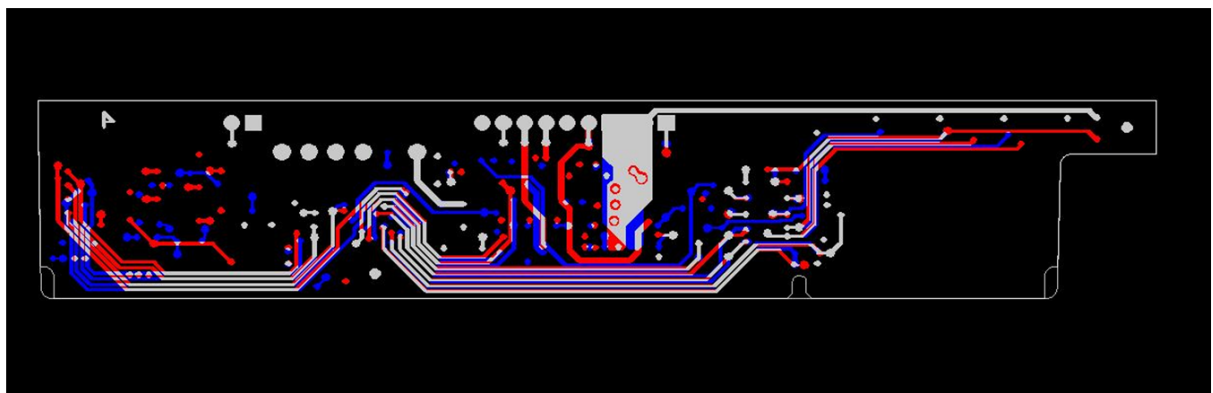
Multilayer 2 V02-layout, black and blue representing holes in the layer,
V06-layout, black and red representing holes in the layer



Bottom view V02-layout



Bottom view V06-layout

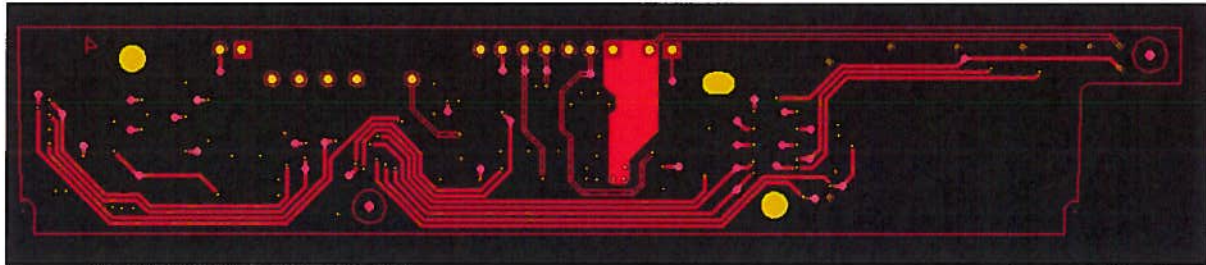


Bottom view - V02-layout red, V06-layout blue

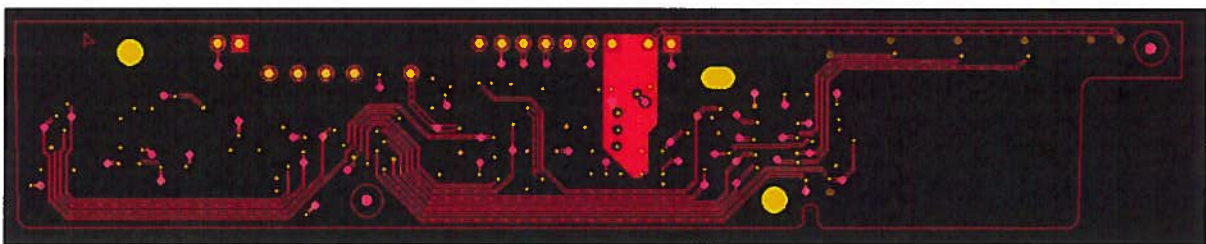
Confirmed by

P. Stauss-Reiner
Development engineer

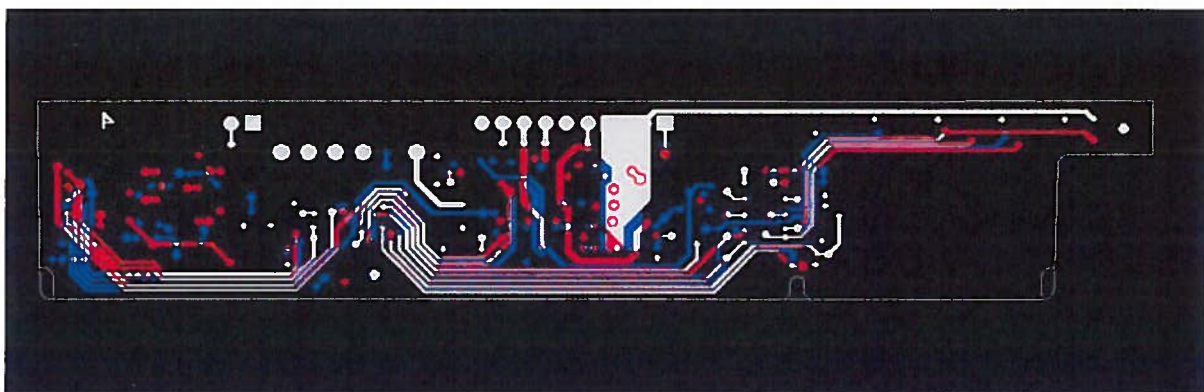
J. Nienstedt
Certification engineer



Bottom view V02-layout



Bottom view V06-layout



Bottom view - V02-layout red, V06-layout blue

Confirmed by

P. Stauss-Reiner

P. Stauss-Reiner
Development engineer

J. Nienstedt

J. Nienstedt
Certification engineer